

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# TPN4R712MD

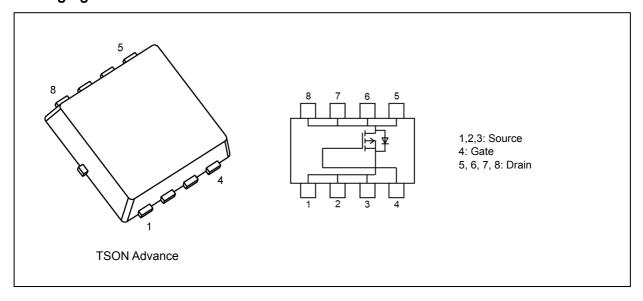
### 1. Applications

- · Lithium-Ion Secondary Batteries
- · Power Management Switches

### 2. Features

- (1) Low drain-source on-resistance:  $R_{\rm DS(ON)}$  = 3.8 m $\Omega$  (typ.) ( $V_{\rm GS}$  = -4.5 V)
- (2) Low leakage current:  $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -20 \text{ V)}$
- (3) Enhancement mode:  $V_{th}$  = -0.5 to -1.2 V ( $V_{DS}$  = -10 V,  $I_D$  = -1.0 mA)

### 3. Packaging and Internal Circuit



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### 4. Absolute Maximum Ratings (Note) (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteri	Symbol	Rating	Unit		
Drain-source voltage			V <sub>DSS</sub>	-20	V
Gate-source voltage			V <sub>GSS</sub>	±12	
Drain current (DC)	(T <sub>c</sub> = 25 °C )	(Note 1)	I <sub>D</sub>	-36	Α
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I <sub>DP</sub>	-180	
Power dissipation	(T <sub>c</sub> = 25 °C )		P <sub>D</sub>	42	W
Power dissipation	(t = 10 s)	(Note 2)	<b>]</b> [	1.9	
Power dissipation	(t = 10 s)	(Note 3)	Ī [	0.7	
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	320	mJ
Single-pulse avalanche current			I <sub>AS</sub>	-36	Α
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics			Symbol	Max	Unit
Channel-to-case thermal resistance	(T <sub>c</sub> = 25 °C)		R <sub>th(ch-c)</sub>	2.97	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	65.7	
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	178	

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{DD}$  = -16 V,  $T_{ch}$  = 25 °C (initial), L = 190  $\mu$ H,  $I_{AS}$  = -36 A

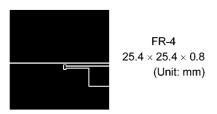


Fig. 5.1 Device Mounted on a Glass-Epoxy

Board (a)

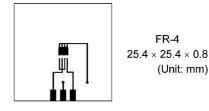


Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V	_	_	-10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-20			V
Drain-source breakdown voltage (Note 5)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 8.0 V	-12	_	_	
Gate threshold voltage	$V_{th}$	$V_{DS} = -10 \text{ V}, I_{D} = -1.0 \text{ mA}$	-0.5	_	-1.2	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -2.5 V, I <sub>D</sub> = -16 A	_	6.0	8.1	mΩ
		$V_{GS} = -4.5 \text{ V}, I_D = -18 \text{ A}$		3.8	4.7	

Note 5: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

## 6.2. Dynamic Characteristics ( $T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	4300	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	640	_	
Output capacitance	C <sub>oss</sub>		_	700	_	
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1.	_	11	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	18	_	
Switching time (fall time)	t <sub>f</sub>		_	145	_	
Switching time (turn-off time)	t <sub>off</sub>			443		

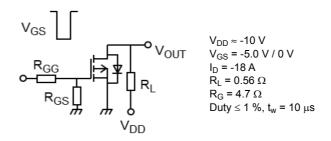


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -16 \text{ V}, V_{GS} = -5.0 \text{ V}, I_{D} = -36 \text{ A}$	_	65		nC
Gate-source charge 1	Q <sub>gs1</sub>		_	7.5	_	
Gate-drain charge	$Q_{gd}$		_	20	_	

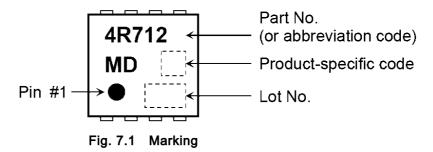
## 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note6)	I <sub>DRP</sub>	_	_	_	-180	А
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = -36 A, V <sub>GS</sub> = 0 V			1.2	V

Note6: Ensure that the channel temperature does not exceed 150°C.



## 7. Marking





### 8. Characteristics Curves (Note)

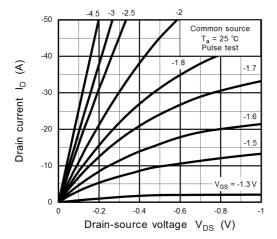


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>

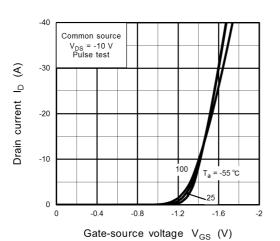


Fig. 8.3 I<sub>D</sub> - V<sub>GS</sub>

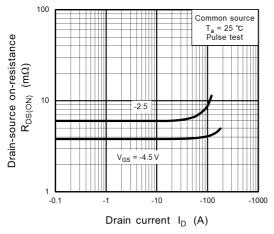


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

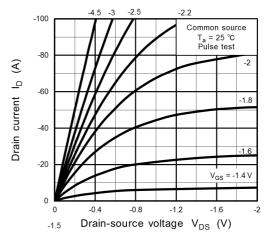


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

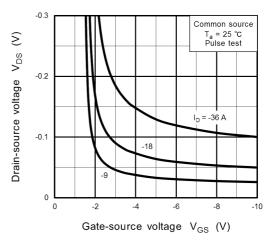


Fig. 8.4 VDS - VGS

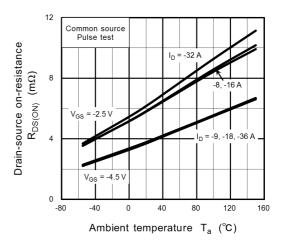


Fig. 8.6 R<sub>DS(ON)</sub> - T<sub>a</sub>



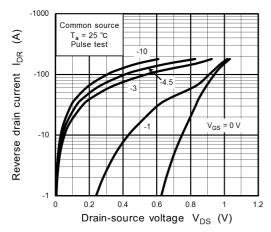


Fig. 8.7 IDR - VDS

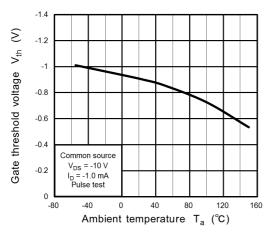


Fig. 8.9 V<sub>th</sub> - T<sub>a</sub>

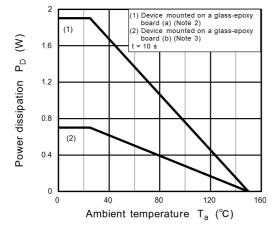


Fig. 8.11 P<sub>D</sub> - T<sub>a</sub> (Guaranteed Maximum)

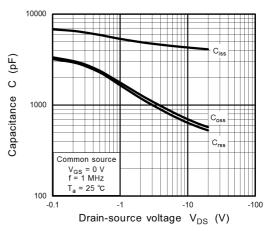


Fig. 8.8 Capacitance - V<sub>DS</sub>

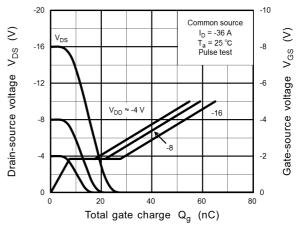


Fig. 8.10 Dynamic Input/Output Characteristics

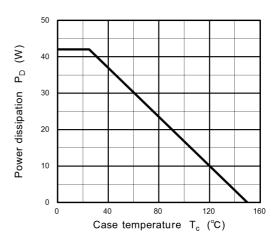


Fig. 8.12 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)



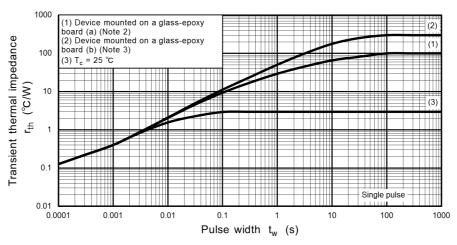


Fig. 8.13 r<sub>th</sub> - t<sub>w</sub> (Guaranteed Maximum)

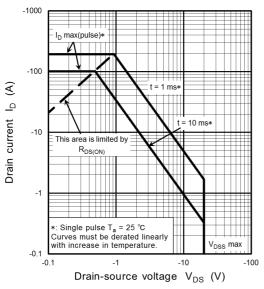


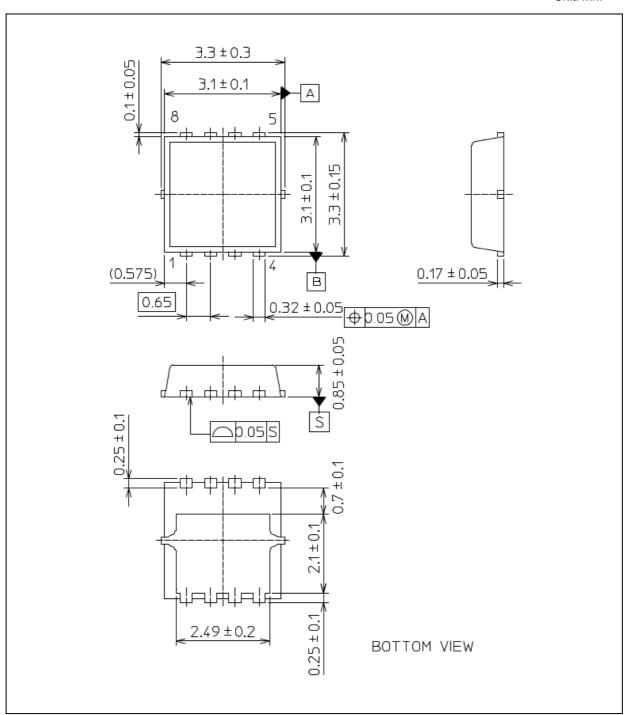
Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.029 g (typ.)

Package Name(s)
TOSHIBA: 2-3X1S
Nickname: TSON Advance

Rev.6.0



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